

Features

- ±2.0% Tolerance on Breakdown Voltage
- Small, Low Profile Surface Mount Package
- Flat Lead Package Design for Low Profile and High Power Dissipation
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

- Case: SOD523
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish - Matte Tin Annealed over Alloy 42 Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (Approximate)



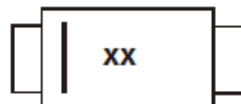
Top View

Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
BZT585B5V1TQ-7	Automotive	SOD523	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product_compliance_definitions/.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



xx = Product Type Marking Code
(See Electrical Characteristics Table)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Forward Voltage	V _F	@ I _F = 10mA	0.9
		@ I _F = 100mA	1.1
Continuous Forward Current	I _F	200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Note: 6. Device mounted on FR-4 PCB with minimum recommended pad layout, as shown in Diodes Incorporated's Suggested Pad Layout document, which can be found on our website at <http://www.diodes.com>.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Type Number	Marking Codes	Zener Voltage Range (Note 7)				Maximum Zener Impedance (Note 8)			Temperature Coefficient	Total Capacitance	Maximum Reverse Current (Note 7)	
		V _Z @ I _{ZT}			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	TC @ I _{ZT}	C _T @ f = 1MHz, V _R = 0V	I _R	@ V _R
		Nom (V)	Min (V)	Max (V)	mA	Ω		mA	Typical (mV/°C)	Max (pF)	μA	V
BZT585B5V1TQ	3N	5.1	5.00	5.20	5	60	480	1	-0.5	300	2	2

Notes: 7. Short duration pulse test used to minimize self-heating effect.
8. f = 1kHz.

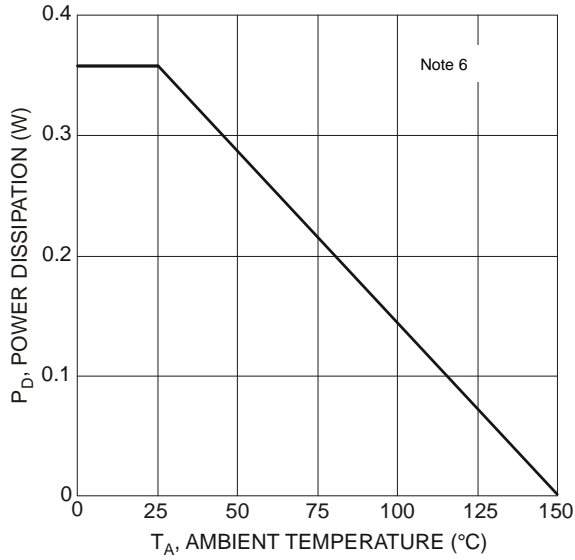


Figure 1 Power Derating Curve

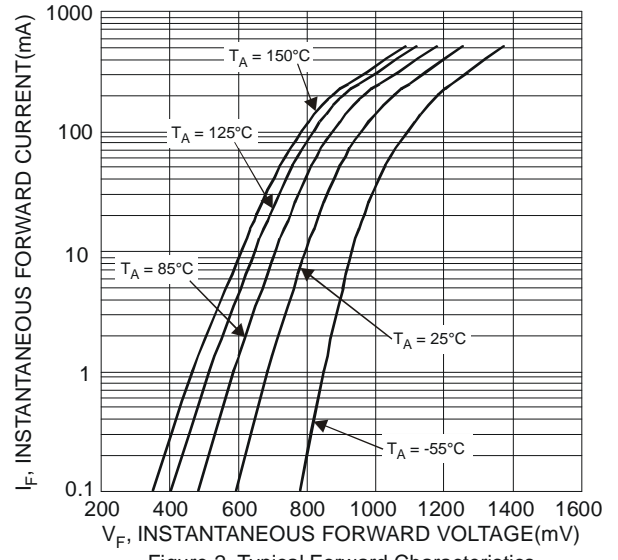


Figure 2 Typical Forward Characteristics

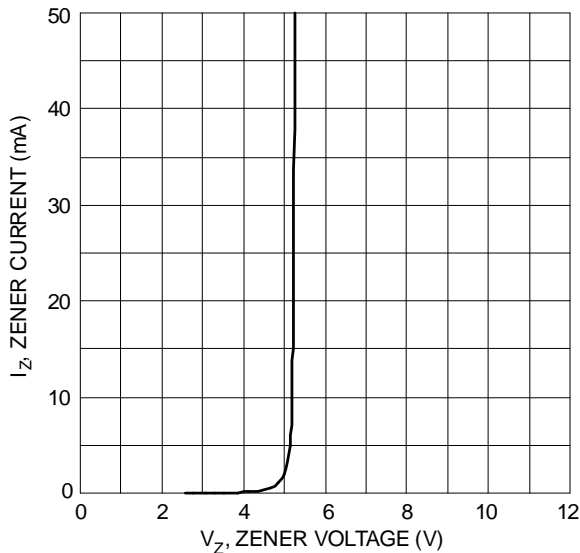
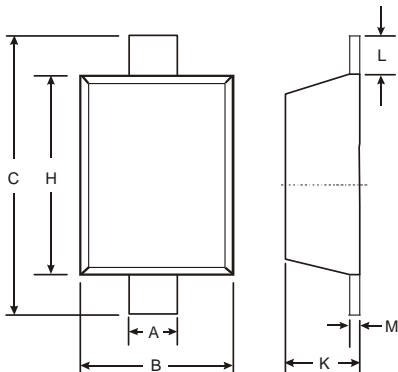


Figure 3 Typical Zener Breakdown Characteristics

Package Outline Dimensions

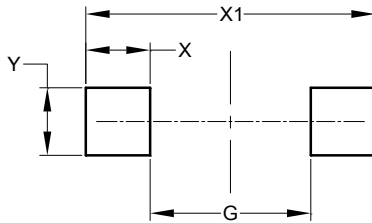
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOD523		
Dim	Min	Max
A	0.25	0.35
B	0.70	0.90
C	1.50	1.70
H	1.10	1.30
K	0.55	0.65
L	0.10	0.30
M	0.10	0.12
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G	0.80
X	0.60
X1	2.00
Y	0.70

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